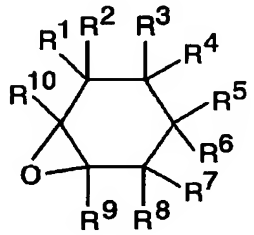
Abstract

The present invention provides a heat-curable resin composition which is curable and is capable of providing a cured product with low shrinkage in curing. The heat-curable resin composition of the present invention includes an alicyclic epoxy compound (a) having a structure represented by the following general formula (1),

General formula (1)



[In the general formula (1): R^1 to R^{10} each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms, and an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group; R^1 to R^{10} may each represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R^1 to R^{10}; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"], a cationic polymerization initiator (i), a surfactant (e), and optionally a polyol (b) having two or more hydroxyl groups on terminals.